



Product Change Notification

#111466 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 111466 - 00
Change Title: Intel® Atom™ Processors D2500 & D2550, PCN 111466-00, Product Design, B-2 to B-3 Stepping Conversion for Tray
Date of Publication: May 17, 2012

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

D2500	
Date of Samples Availability:	June 11, 2012
Date of Qualification Data Availability:	July 9, 2012
Date of First Availability of Post-Conversion Material:	July 16, 2012
Date Customer Must be Ready to Receive Post-Conversion Material:	July 23, 2012

D2550	
Date of Samples Availability:	June 18, 2012
Date of Qualification Data Availability:	July 9, 2012
Date of First Availability of Post-Conversion Material:	July 16, 2012
Date Customer Must be Ready to Receive Post-Conversion Material:	July 23, 2012

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Intel® Atom™ Processors D2500 & D2550 will undergo the following changes for the B-2 to B-3 stepping:

1. Change in Host Revision ID (PCI Device B0:D0:F0) to 0x04h and change in Graphics Revision ID (PCI Device B0:D2:F0) to 0x0Bh.
2. Fix for Erratum Number BQ22 documented in the Intel® Atom™ Processor N2000 and D2000 Series Specification Update (Document number 326140-008). Erratum status, shown as "No Fix" in the Specification Update, will be updated in the next revision of the Specification Update.
3. Erratum BQ22 has been fixed in B-3 stepping silicon and B-3 stepping silicon will not require the Graphics driver workaround provided for the B-2 stepping.

Customer Impact of Change and Recommended Action:

1. Graphics driver change is required for the B-3 stepping. BIOS changes are required in order for B-3 stepping information to be displayed in the BIOS menu. Please refer to Qualification Samples Dear Customer Letter (DCL) for details.
2. Intel anticipates minimal validation.
3. New S-Spec and new MM numbers are required for the B-3 stepping. See products listed in the "Products Affected/Intel Ordering Codes" table below.

Products Affected / Intel Ordering Codes:

Processor#	Frequency	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#	Post Conversion Qualification Samples QDF#	Post Conversion Qualification Samples MM#	Post Conversion Product Code	Post Conversion S-Spec	Post Conversion MM#
D2500	1.86GHz	DF8064101055400	SR0D8	915980	QCYA	922892	DF8064101055400	SR0W0	922893
D2550	1.86GHz	DF8064101211300	SR0QB	920186	QCY8	922868	DF8064101211300	SR0VY	922869

PCN Revision History:

Date of Revision:

May 17, 2012

Revision Number:

00

Reason:

Originally Published PCN